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SPDT PART NUMBER SELECTION GUIDE^[1]

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Series	CUIIIBUIAUUI	- DC - 8 GH			2HP 5.02 - JU	SMA 3 GHz	SMA 6 GHz	SMA 18 GHz	SMA 20 GHz	SMA 26.5 GHz	SMA 2.9 40 GHz	2.4mm 50 GHz	QMA 6 GHz	DIN 1.6/5.6, 2.5 GHz		Pc board mount 3 GHz	N 3 GHz	N 12.4 GHz	BNC 3 GHz	TNC 3 GHz	TNC 12.4 GHz	TNC 18 GHz	Failsafe	Latching	6 V	12 V	15 V	24 V	28 V	Without	With	SPDT non-terminated		Without option	Positive common	Supression diodes	Suppression diodes and positive common	Compatible with TTL driver		Not soldered	Soldered on a connectorized test fixture	Solder pins	D-Sub connector	Certificate of conformity	Calibration certificate	רמווחו מרוחדו רבו רווורמרב
PLATINUM		CVC X	1	8	I	ı	m		4	ш	~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~	1	1	,	1	1		1	I	I	1	ı	I	3/4/5/6	1	ı	7	m	ı	1	ı	1	I	1	1	I	1	2	ı	1	ı	0	S	1	U	,
SES		K5/U	1		ı	m	I	4	1	ш	~~~	_	ш	6	т	A	1	1	I		ı		1/2	3/4/5/6	ı	2		ı	m	0	~	ı	I	0	1	m	4		1	I		0	1		1	
RAMSES		K5/U			1	ı	I		1	1		1	1	1	1		0	-	2	5	9	۵	1/2	3/4/5/6	ı	2			m	0	~		I	0	1	m	4	ı	1	1	1	0	5			
Quartz		K516	0 <	1 1	_			ı		1	,		1	,	1	1					,		1/9	m	-	2		m	1				1		,			1	0	0	F	1				

Notes

Example of P/N: R570F12010 is a SPDT SMA 26.5 GHz, failsafe, 12 Vdc, without TTL, with positive common, solder pins.

1. For part number creation and available options, see detailed part number selection for each series.



SMT POWER MICRO SPDT WITH 26.5 GHz CAPABILITIES SURFACE MOUNT TECHNOLOGY

An innovative and original "micro-mechanical" design of the R516 SMT micro-relay offers excellent RF performance, reliability, and repeatability. The miniature size and low installation cost make these coaxial switches an ideal solution.

Very low return loss and insertion loss allow this relay to be used in power applications, as well as in typical SMT relay applications such as RF attenuators, RF matrices, spectrum analysers, and telecommunications.

Failsafe models are offered in two RF configurations (direct and inverted). The association of these two products on the same PC board enables the product to perform the bypass function. (For bypass mounting, further information is available on page 2-7.)



Example of P/N:

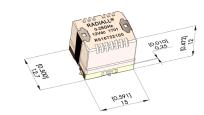
R516713100 is a SPDT SMT 26.5 GHz, 24 Vdc, failsafe, not soldered.

ACTUAL SIZE



TYPICAL OUTLINE DRAWING

All dimensions are in millimeters [inches].



PART NUMBER SELECTION	R516	10	
SERIES PREFIX			ACTUATOR TERMINALS
FREQUENCY RANGE 3: DC – 8 GHz 4: DC – 18 GHz			0: Not soldered T: Soldered on a connectorized test fixture ^[2]
7: DC – 26.5 GHz			
ТҮРЕ			1: 6 Vdc ^[3] 2: 12 Vdc
1: Failsafe 3: Latching, 2 coils 9: Failsafe, inverted RF path ^[1]			3: 24 Vdc

Notes:

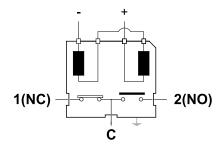
- 1. Can be combined with a failsafe model, so as to achieve the "BYPASS" function (see application details on page 2-6).
- See details about test fixture dimensions on page 2-4.
 Only available with type 3.

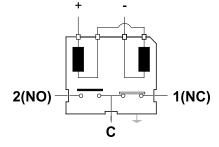


QUARTZ GENERAL SPECIFICATIONS

OPERATING MODE		FAILSAFE (TYPES 1 & 9)	L	ATCHING (TYPE	3)			
Nominal operating voltage (across temperature range)	Vdc	12 (10.5 to 13)	24 (21.5 to 30)	6 (5.1 to 6.6)	12 (10.2 to 13)	24 (20.5 to 30)			
Coil resistance at 23 °C (+/- 10%)	Ω	195	710	55	205	865			
Operating current at 23 °C	mA	61	32	108	58	32			
RF and command ports		Gold-plat	ted access, infrare (Compatible with						
Switching time at nominal voltage - Making contacts - Breaking contacts		M	lax 5 ms (typical 2	ms), including co 3 ms), including contact bounce time				
Life - Cold switching (max 120 cycles/min)		2 millio	n cycles	(5 million	3 million cycles million cycles typical at low level)				
- Hot switching (max 20 cycles/min)				500.000 cycles					
		Dielectric	test voltage		300 Vrms				
Insulation			esistance at) Vdc		> 100 MOhms				
Environmental protection		Lead	free construction	- Waterproof (a	icc. To IEC 60529	/ IP64)			
Mass				8 g					
Operating temperature range (with no icing nor condensation)	°C	-25 to	o +70 ^[1]		-40 to +85 -55 to +85				
Storage temperature range	°C			-55 to +85					
	(5)	Condition D: 10	Operating						
Sine vibration (MIL STD 202, Method 204D) Condition G: 10-2,000 Hz, 30 g Non-operating									
Shocks (According to MIL STD 202, Method 213	B, Cond. C)	100 g / 6 n	ns, 1/2 sine		Operating				

PIN IDENTIFICATION (TOP VIEW)



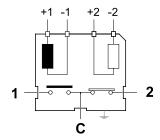


FAILSAFE MODEL (TYPE 1)

VOLTAGE	RF CONTINUITY
De-energized	C <> 1(NC)
Energized	C <> 2(NO)

INVERTED FAILSAFE MODEL FOR BYPASS APPLICATION (TYPE 9)

VOLTAGE	RF CONTINUITY
De-energized	C <> 1(NC)
Energized	C <> 2(NO)



LATCHING MODEL (TYPE 3)

VOLTAGE	RF CONTINUITY
-1 +1	C <> 1
-2 +2	C <> 2

Notes

1. Failsafe models may be used down to -40 °C, for this application please follow requirements of AN-R516-51. Contact Radiall for a copy of this application note.

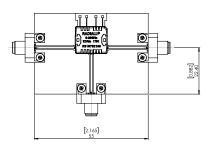


QUARTZ PERFORMANCE (S PARAMETERS AVAILABLE ON REQUEST)

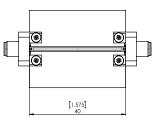
FREQUENCY RANGE		V.S.W.R.	INSERTION LOSS	ISOLATION (MIN) dB	THIRD ORDER INTER	IMPEDANCE		
GI	Hz	(MAX)	(MAX) dB	SWITCH ALONE	MODULATION	Ω		
	DC – 3	1.20	0.20	50				
	3 - 6	1.35	0.40	40				
DC - 8	6 - 8	1.40	0.50	40	-110 dBc typical at	50		
DC – 18 DC – 26.5	8 - 12.4	1.50	1.50 0.60 40	1730 MHz (2 carriers 20 W)	50			
	12.4 - 18	1.70	1.00	40				
	18 - 26.5	2.00	1.60	40				

MEASUREMENT METHOD

RELAY SOLDERED ON TEST FIXTURE^[1]

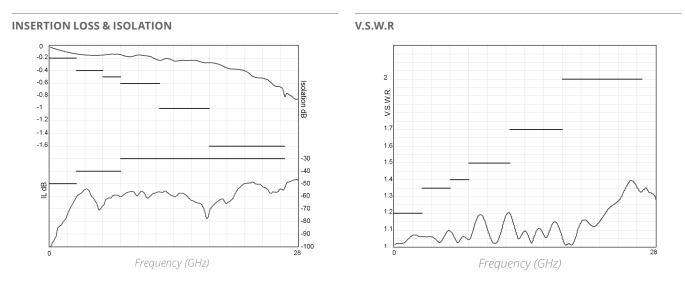


CALIBRATION BOARD



Inputs/Outputs of the calibration board and test fixture are equipped with coaxial type receptacle connectors. The length of the RF tracks is the same on the calibration board and the test fixture circuits. The insertion loss of the relay itself is calculated by subtracting the insertion loss of the "calibration board" to the insertion loss of the "relay soldered on the test fixture."

TYPICAL RF PERFORMANCE



Notes

1. Relay soldered on Test Fixture is available. To order, please use the suffix "T" (part number R516 - - - - T), as explained in page 2-2. All dimensions are in millimeters [inches].



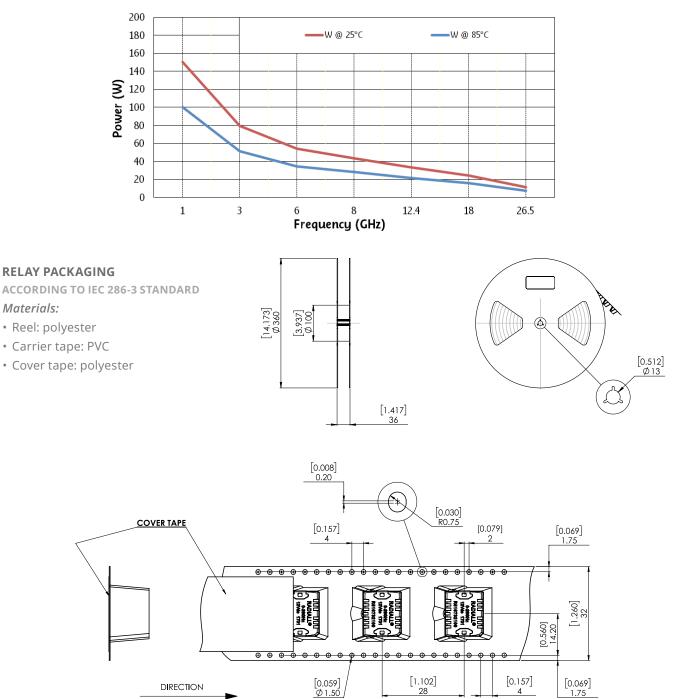
Materials:

RF POWER RATING FOR COLD SWITCHING USE

(IMPEDANCE 50 OHMS, V.S.W.R. < 1.25)

Power level depends on environmental conditions:

- R516 series have been designed to be used without a cooling fan even for high power applications. However, the power capability may be still improved by using the appropriate cooling fan.
- · For failsafe models used with coil permanently supplied (N/O position), the same power level as latching models may be applied.

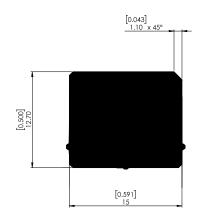




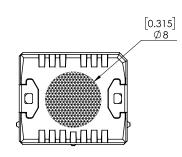
OF FEED

4

VIDEO SHADOW OF THE RELAY

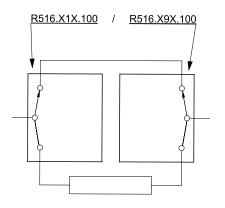


ASPIRATION AREA



BYPASS APPLICATION

FAILSAFE MICRO-RELAY TYPICAL IMPLANTATION

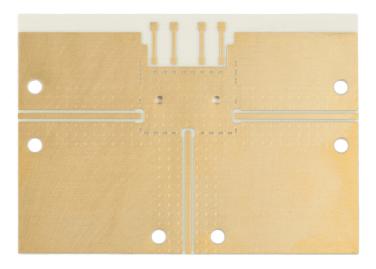


SPDT relays (Single Pole Double Throw) can be used to achieve a bypass switch function. For SMT applications, R516 series, relays are available in two failsafe versions, standard and inverted, to provide symmetric RF ports implantation possibility. The "side by side" implementation of these two versions on a PCB effectively produces the bypass function. The package size is reduced and interconnecting tracks are shortened. Required in order to protect the receiver for transmit/receive applications. RF performance of bypass switch assemblies depend on the distance between the two RF SMT relays.

PC BOARD MOUNTING

Board layout

DXF or Gerber format file available upon request.



SUBSTRATE TYPES

Recommended substrates are ROGERS RO4003. Thickness 0.508 mm Cu double side 17.5 μm.

Recommended total thickness of RF tracks (copper over thickness + plating): 40 μm. Other substrates may be used.



RECOMMENDED SOLDERING PROCEDURE

A - Soldering procedure using automatic pick and place equipment

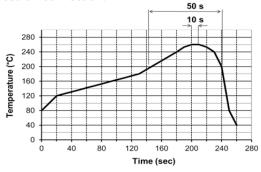
1 - Solder paste: R516 series are "Lead Free", and Lead Free Sn-Ag3.5-Cu0.7 solder cream may be used as well as standard Sn63–Pb35–Ag2. Radiall recommends using a "no clean - low residue" solder cream (5% solid residue of flux quantity) that will permit the elimination of the cleaning operation step after soldering.

Note: Due to the gold plating of the switch PCB interface, it is important to use a paste made with silver. This will help in avoiding formation of intermetallics as part of the solder joint.

2 - Solder paste deposition: Solder cream may be applied on the board with screen printing or dispenser technologies. For either method, the solder paste must be coated to appropriate thickness and shapes to achieve good solder wetting. Please optically verify that the edges of the zone are clean and without contaminates, and that the PCB zoned areas have not oxydated. The design of the mounting pads and the stenciling area are available upon request, for a thickness of the silk-screen printing of 0.15 mm (0.006 ".)

3 - Placement of the component: For small lightweight components such as chip components, a self-alignment effect can be expected if small placement errors exist. However, this effect is not as expected for relays components and they require a accurate positioning on their soldering pads, typically +/- 0.1 mm (+/-0.004".) Place the relay onto the PCB with automatic pick and place equipment. Various types of suction can be used. Radiall does not recommend using adhesive agents on the component or on the PCB.

4 - Soldering: infrared process: Please follow the Radiall recommended max temperature profile for infrared reflow or forced air convection:





Higher temperature (>260 °C) and longer process duration would permanently damage the switches. **5 - Cleaning procedure:** On miniature relays, high frequency cleaning may cause the contacts to stick. If cleaning is needed, please avoid ultrasonic cleaning and use alcohol based cleaning solutions.



In-line cleaning process, spraying, immersion, especially under temperature, may cause a risk of degradation of internal contacts. For such cleaning process please contact us.

6 - Quality check: Verify by visual inspection that the component is centered on the mounting pads. Solder joints: verify by visual inspection that the formation of meniscus on the pads are proper.

B – Soldering procedure by manual operation



Manual soldering is not recommended for high frequencies, as it generates resonance and lower RF characteristics due to gaps between PC board and relay grounds.

1 - Solder paste and flux deposition: Refer to procedure
A – 1. Deposit a thin layer of flux on solder pad area.
Allow the flux to evaporate a few seconds before applying the solder paste, it will prevent dilution of the paste.

2 - Solder paste deposition: Radiall recommends depositing a small amount of solder paste on solder pad area by syringe, according to the manual soldering pattern (available upon request.) Be careful not to apply solder paste outside of the zone area.

3 - Placement of the component: During manipulation, avoid contaminating gold surfaces by contact with fingers. Place the component on the mounting zone by pressing on the top of the relay lid.

4 - Hand soldering: Iron wattage 30 to 60 W. To keep better RF characteristics, apply pressure on the relay lid during all the soldering stage, so as to reduce the air gap between the PC board and the relay. If possible, fix the ground plane of the relay on the board with two M1.2 screws before the soldering stage. On each side of the central RF access, the RF body edge must be soldered to the ground of the PC board. To improve RF characteristics and avoid soldering the RF body to the ground, a conductive gasket may be used (please contact us for detailed application note.)

5 - Cleaning procedure: Refer to procedure A – 5.

6 - Quality check: Verify by visual inspection that component is centered on the mounting pads. Solder joints: verify by visual inspection that there is no solder excess on the RF pads.



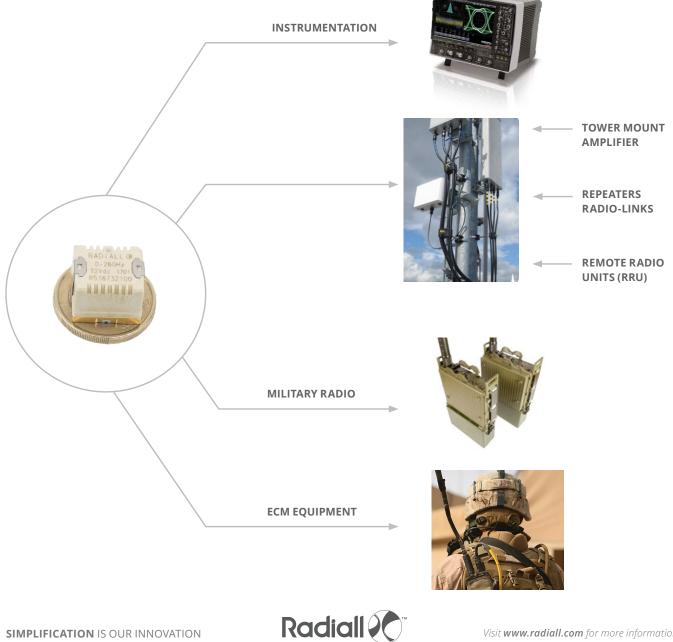
APPLICATIONS

PC BOARD MOUNTING

The SMT Series offers a large range of products which can be used in many applications such as:

- Tower mount amplifiers
- Instrumentation
- Military radios
- ECM equipment
- Remote Radio Unit (RRU)
- Radio-Links
- Repeaters

These products offer the same RF Board and soldering process as all RF components but with a reduced weight and size. They are designed to meet all market specifications.



SPDT UP TO 50 GHz

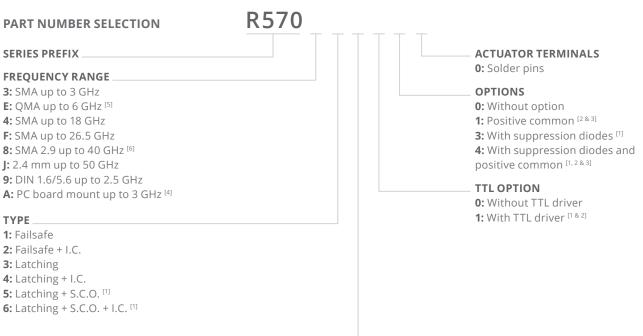
PC BOARD - SMA - SMA 2.9 - 2.4 MM - QMA - DIN 1.6/5.6



Radiall's RAMSES SPDT switches offer excellent reliability, high performance and operating frequencies from DC to 50 GHz. Radiall's RAMSES concept (which provides for a life span of 10 million cycles) offers a variety of options to meet customer needs.

These switches are dedicated to all market applications including: military, instrumentation and telecommunications.

Example of P/N: R570413100 is a SPDT SMA 18 GHz, failsafe, 28 Vdc, with TTL driver, without option, solder pins.



ACTUATOR VOLTAGE

2: 12 Vdc 3: 28 Vdc

Notes:

- I.C.: Indicator contact S.C.O.: Self Cut-Off.
- 1. Suppression diodes are already included in Self Cut-Off and TTL option.
- 2. Polarity is not relevant to application for switches with TTL driver.
- *3.* Positive common shall be specified only with type 3, 4, 5, and 6 because failsafe switches can be used with both polarities.

4. Available only upon request.

- 5. The QLF tradermark (Quick Lock Formula®) standard applies to QMA and QN series and guaranties the full intermateability between suppliers using this tradermark. Using QLF certified connectors also guarantees the specified level of RF performance.
- 6. Connector SMA 2.9 is equivalent to "K connector®", registered trademark of Anritsu.





GENERAL SPECIFICATIONS

OPERAT	TING MODE		FAIL	SAFE	LA	TCHING
	Nominal operating voltage (across temperature range)		12 (10.2 to 13)	28 (24 to 30)	12 (10.2 to 13)	28 (24 to 30)
Coil resistance at 23 °C (+/-10%)		Ω	47.5	275	58	350
Operating current	at 23 °C	mA	250	102	210	80
Avera	ge power			See Power	Rating Chart page 1-1	3
TTL Input		High level	2.2 to 5	5.5 Volts	1 Aμ 008	max 5.5 Volts
TTL Input		Low level	0 to 0.	8 Volts	20 µA n	nax 0.8 Volts
Indicator rating			1 W / 30 V / 100 mA			
Switching time ms		10				
	SMA - SMA 2.9 - QMA		10 million cycles			
Life	DIN 1.6/5.6 - PC	Board	5 million cycles			
	2.4 mm		2 million cycles			
Con	nectors		SMA - SMA 2.9 - QMA - DIN 1.6/5.6 - PC Board - 2.4 mm			
Operating temperature	DIN 1.6/5.6 - 2.	4 mm	-25 °C to +70 °C			
Operating temperature range	SMA - SMA 2.9 - PC Board		-40 °C to +85 °C			
	DIN 1.6/5.6 - 2.	4 mm	-40 °C to +85 °C			
Storage temperature range SMA - SMA 2.9 - QMA - PC Board		-55 °C to +85 °C				
Vibration (MIL STD 20	2, Method 204D, cond	d.D)	10-2,000 Hz, 20 g Operating			perating
Shock (MIL STD 202	, Method 213B, cond.	C)	100 g / 6 i	ms, ½ sine	Op	erating

RF PERFORMANCE

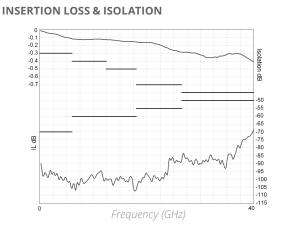
CONNECTORS	ONNECTORS FREQUENCY		V.S.W.R. (MAX)	INSERTION LOSS (MAX) dB	ISOLATION (MIN) dB	IMPEDANCE Ω	
DIN 1.6/5.6		DC - 1	1.20	0.20	80	75	
DIN 1.0/5.0	DC - 2.5	1 - 2.5	1.30	0.30	70	75	
0144	QMA DC - 6	DC - 3	1.20	0.20	80		
QIMA		3 - 6	1.30	0.30	70		
		DC - 3	1.10	0.15	80		
	DC - 3	3 - 8	1.20	0.20	75		
SMA	DC - 18	8 - 12.4	1.20	0.25	65		
DC - 26.5	12.4 - 18	1.40	0.35	60			
		18 - 26.5	1.50	0.50	55		
	DC - 6	1.30	0.30	70			
	6 - 12.4	1.40	0.40	60			
SMA 2.9	DC - 40	12.4 - 18	1.50	0.50	60	50	
		18 - 26.5	1.70	0.70	55		
		26.5 - 40	1.90	0.80	50		
PC Board	DC - 3	DC - 3	1.20	0.20	80		
		DC - 6	1.30	0.30	70		
		6 - 12.4	1.40	0.40	0.40 60		
2.4 mm DC - 50		12.4 - 18	1.50	0.50	60	1	
	DC - 50	18 - 26.5 1.70 0.70	55				
		26.5 - 40	1.90	0.80	50		
		40 - 50	1.90	1.10	50		

Notes

See page 2-12 and 2-13 for typical RF performance.

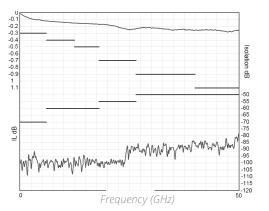
R570 TYPICAL RF PERFORMANCE

Example: SPDT SMA 2.9 up to 40 GHz



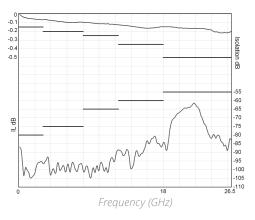


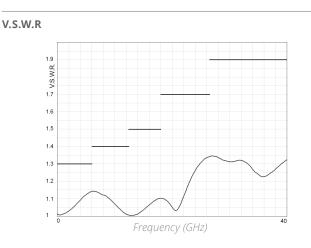
INSERTION LOSS & ISOLATION



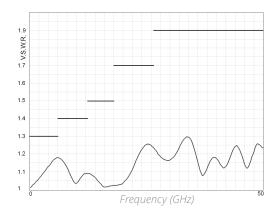


INSERTION LOSS & ISOLATION

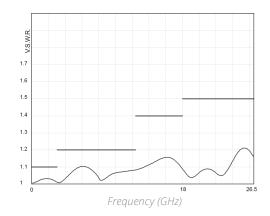




V.S.W.R



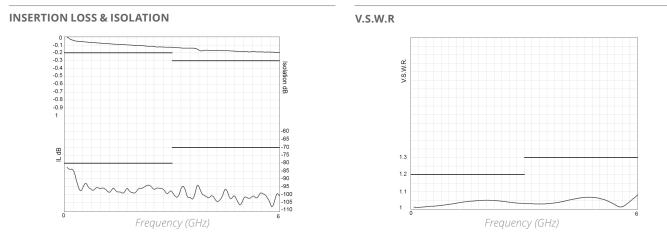






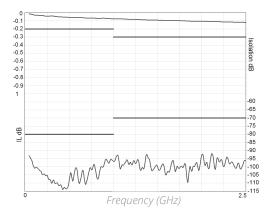
R570 TYPICAL RF PERFORMANCE (CONTINUED)

Example: SPDT QMA up to 6 GHz

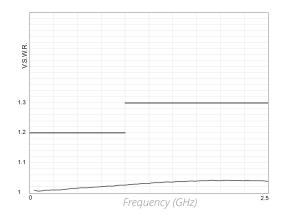


Example: SPDT DIN 1.6/5.6 up to 2.5 GHz

INSERTION LOSS & ISOLATION



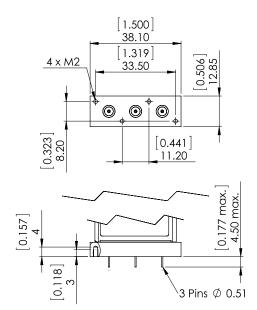
V.S.W.R

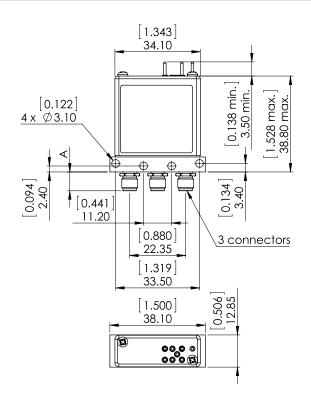




TYPICAL OUTLINE DRAWING

CONNECTORS	A MAX (MM [INCHES])			
SMA	7.7 [0.303]			
SMA 2.9 and 2.4 mm	6.7 [0.264]			
QMA	10.8 [0.394]			
DIN 1.6/5.6	11.5 [0.433]			
PC Board	4.5 [0.157]			

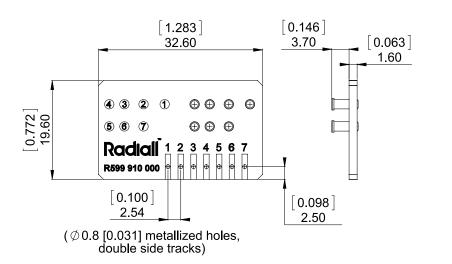




Notes See page 2-23 for pin identification. All dimensions are in millimeters [inches].

ACCESSORIES

A printed circuit board interface connector (ordered separately) has been designed for easy mounting on terminals. For SPDT model R570 series = Radiall part number: R599 910 000.





Notes All dimensions are in millimeters [inches]. The PCB accessory pin number assignment is independent from the pin identification table of the switch.

SPDT UP TO 18 GHz

N - TNC - BNC



Radiall's RAMSES SPDT N, BNC and TNC switches are designed for high performance in RF & Microwave systems up to 18 GHz.

Radiall's RAMSES concept (modular concept) offers a full range of configurations. They are commonly used for applications where high power handling capability is required.

These switches are dedicated to all market applications including: defense, instrumentation and telecommunications.

Example of P/N: R570113035 is a SPDT N 12.4 GHz, failsafe, 28 Vdc, with supression diodes, without option, D-Sub connector.



2: 12 Vdc 3: 28 Vdc

Notes

I.C.: Indicator contact - S.C.O.: Self Cut-Off.

1. Suppression diodes are already included in Self Cut-OFF and TTL option.

2. Polarity is not relevant to application for switches with TTL driver.

3. Positive common shall be specified only with type 3, 4, 5 and 6 because failsafe switches can be used with both polarities.



GENERAL SPECIFICATION

	OPERATING MODE		FAI	LSAFE	LATC	HING	
Nominal operating voltage) (d a	12	28	12	28	
(across	s temperature range)	Vdc	(10.2 to 13)	(24 to 30)	(10.2 to 13)	(24 to 30)	
Coil resis	stance at 23 °C (+/-10%)	Ω	38	200	38	225	
Opera	ating current at 23 °C	mA	320	140	320	125	
	Average power			See Power Ratin	g Chart page 1-13		
TTI innut	High level		2.2 to 5.5 Volts / 800 µA max 5.5 Volts				
TTL input Low level			0 to 0.8 Volts / 20 µA max 0.8 Volts				
I	Indicator rating	ms	1 W/30 V/100 mA				
	Switching time	ms	10				
	Life		2.5 million cycles				
	Connectors		N - TNC - BNC				
	Actuator terminals		Solders pins or 9 pin D-Sub connector				
Op	perating temperature range		-40 °C to +85 °C				
Storage temperature range			-55 °C to +85 °C				
Vibration (MIL STD 202, Method 204D, cond.D)			10 - 2,000 Hz, 20 g Operating			ating	
Shock (M	IL STD 202, Method 213B, cond.C)		100 g, 6 ms, ½ sine Non-operating				

RF PERFORMANCE

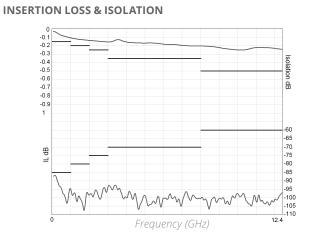
CONNECTORS	FREQUENCY RANGE GHz		V.S.W.R. (MAX)	INSERTION LOSS (MAX) dB	ISOLATION (MIN) dB	IMPEDANCE Ω
		DC - 1	1.15	0.15	85	
		1-2	1.20	0.20	80	
N/TNC	DC - 3 DC - 12.4	2 - 3	1.25	0.25	75	
		3 - 8	1.35	0.35	70	
		8 - 12.4	1.50	0.50	60	
	TNC 18 DC - 18	DC - 6	1.30	0.30	70	50
TNC 18		6 - 12.4	1.50	0.50	60	
		12.4 - 18	1.60	0.70	60	
		DC - 1	1.15	0.15	85	
BNC DC - 3	1 - 2	1.20	0.20	80		
		2-3	1.25	0.25	75	

Notes See page 2-18 for typical RF performance.



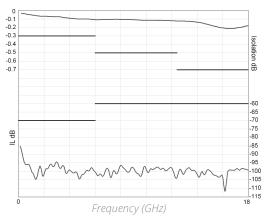
R570 TYPICAL RF PERFORMANCE

Example: SPDT N and TNC up to 12.4 GHz



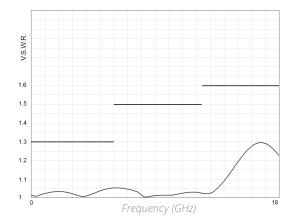
Example: SPDT TNC up to 18 GHz

INSERTION LOSS & ISOLATION

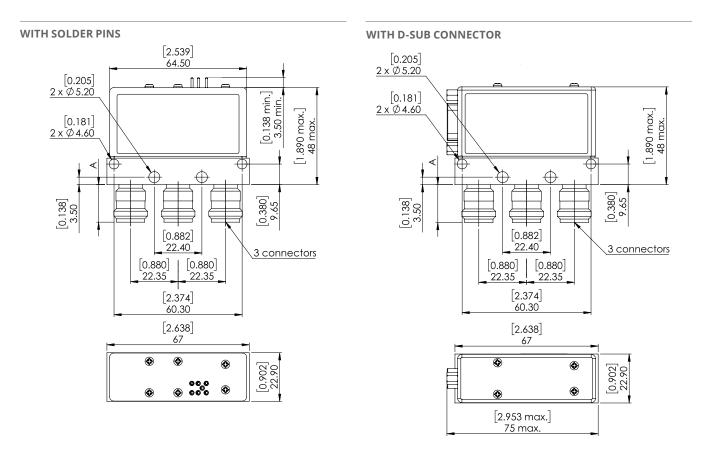


V.S.W.R

V.S.W.R



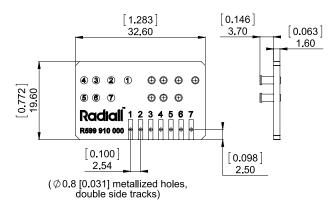
TYPICAL OUTLINE DRAWING



CONNECTORS	Ν	TNC	BNC	
A max (mm [inches])	18.5 [0.709]	11.5 [0.433]	11.5 [0.433]	

ACCESSORIES

A printed circuit board interface connector (ordered separately) has been designed for easy mounting on terminals. For SPDT model R570 series = Radiall part number: R599 910 000





Notes

All dimensions are in millimeters [inches].

The PCB accessory pin number assignment is independant from the pin identification table of the switch.



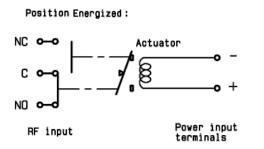
Electrical Schematics

COAXIAL SPDT

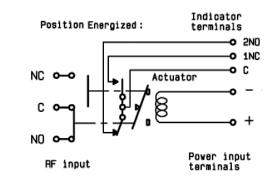
R570 SERIES

FAILSAFE

WITHOUT OPTION R570-1-000



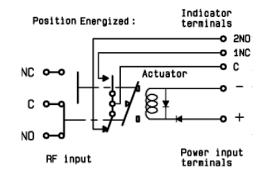
WITH INDICATOR CONTACT R570-2-000



WITH SUPPRESSION DIODES R570-1-030

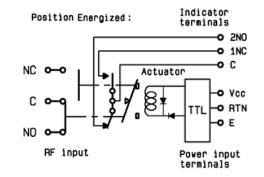
R570-1-100

WITH SUPPRESSION DIODES & INDICATOR CONTACT R570-2-030



WITH TTL DRIVER & INDICATOR CONTACT (SUPRESSION DIODES ARE INCLUDED) R570-2-100

Radial

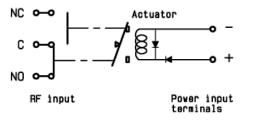


NC O-O C O-O NO O-O RF input RF input RF input

WITH TTL DRIVER (SUPRESSION DIODES ARE INCLUDED)

Position Energized:



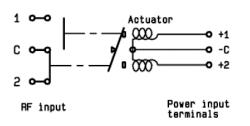


COAXIAL SPDT

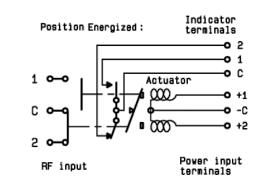
R570 SERIES

LATCHING

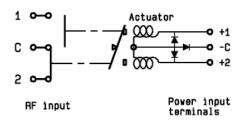
WITHOUT OPTION R570-3-000

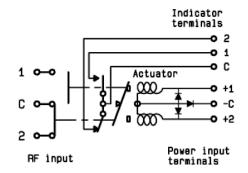


WITH INDICATOR CONTACT R570-4-000

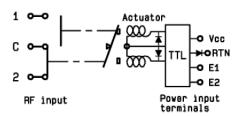


WITH SUPPRESSION DIODES R570-3-030 WITH SUPPRESSION DIODES & INDICATOR CONTACT R570-4-030

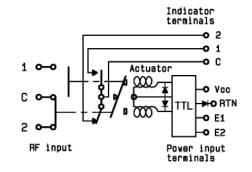




WITH TTL DRIVER (SUPRESSION DIODES ARE INCLUDED) R570-3-100



WITH TTL DRIVER & INDICATOR CONTACT (SUPRESSION DIODES ARE INCLUDED) R570-4-100



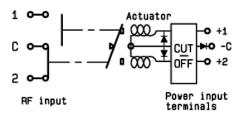
Electrical Schematics

COAXIAL SPDT (CONTINUED)

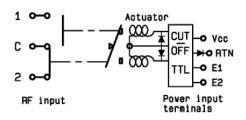
R570 SERIES

LATCHING

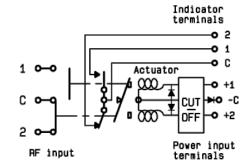
WITH CUT-OFF (SUPRESSION DIODES ARE INCLUDED) R570-5-100



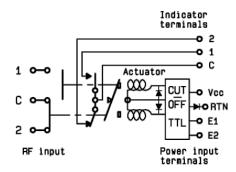
WITH CUT-OFF & TTL DRIVER (SUPRESSION DIODES ARE INCLUDED) R570-5-100



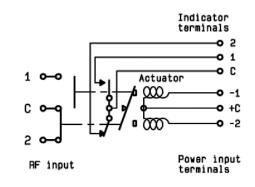
WITH CUT-OFF & INDICATOR CONTACT (SUPRESSION DIODES ARE INCLUDED) R570-6-100



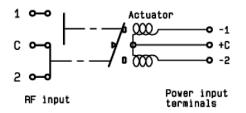
WITH CUT-OFF & INDICATOR CONTACT (SUPRESSION DIODES ARE INCLUDED) R570-6-100



WITH POSITIVE COMMON & INDICATOR CONTACT R570-5-010



WITH POSITIVE COMMON, NO OPTION R570-3-010



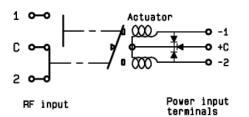
Electrical Schematics

COAXIAL SPDT (CONTINUED)

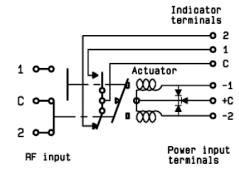
R570 SERIES

LATCHING

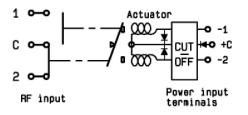
WITH POSITIVE COMMON & SUPPRESSION DIODES R570-3-040

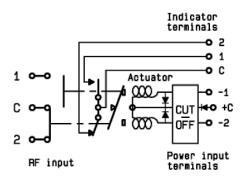


WITH POSITIVE CUT-OFF (SUPRESSION DIODES ARE INCLUDED) R570-5-010 WITH POSITIVE COMMON, SUPPRESSION (DIODES & INDICATOR CONTACT) R570-4-040



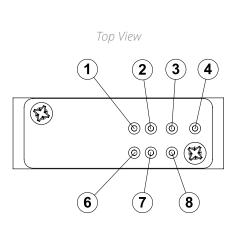
WITH POSITIVE COMMON, CUT-OFF & INDICATOR CONTACT (SUPRESSION DIODES ARE INCLUDED) R570-6-010





PIN IDENTIFICATION

ТҮРЕ	PIN								
ITPE	1	2	3	4	6	7	8		
Failsafe	+		-						
Failsafe + I.C.	+		-		2NO	1NC	С		
Failsafe + TTL	E		RTN	VCC					
Failsafe + I.C. + TTL	E		RTN	VCC	2NO	1NC	С		
Latching Latching + Cut-off	-2 or +2	-1 or +1	+C or -C						
Latching + I.C. Latching + I.C. + Cut-off	-2 or +2	-1 or +1	+C or -C		2	1	С		
Latching + TTL Latching + TTL + Cut-off	E2	E1	RTN	VCC					
Latching + TTL + I.C. Latching + TTL + I.C.+ Cut-off	E2	E1	RTN	VCC	2	1	С		





HIGH PERFORMANCE SPDT UP TO 40 GHz

SMA - SMA 2.9



Radiall's PLATINUM series switches are optimized to perform at a high level over an extended life cycle, with outstanding RF performance, and a guaranteed insertion loss repeatability of 0.03 dB over a life span of 10 million switching cycles. PLATINUM series switches are perfect for automated test and measurement equipment, as well as signal monitoring devices.

Example of P/N: R595443125 *is a SPDT SMA 20 GHz, latching, 24 Vdc, with TTL driver, Indicators, D-Sub connector.*

R595

PART NUMBER SELECTION

SERIES PREFIX

FREQUENCY RANGE

3: SMA up to 6 GHz
4: SMA up to 20 GHz
F: SMA up to 26.5 GHz
8: SMA 2.9 up to 40 GHz

TYPE

3: Latching ^[1] **4:** Latching + I.C. ^[1] **5:** Latching + S.C.O. ^[1] **6:** Latching + S.C.O. + I.C. ^[1]

ACTUATOR VOLTAGE

3: 24 Vdc **7:** 15 Vdc

SWITCH MODEL

1: Non-terminated SPDT switch

OPTIONS 1: Without option (positive common) 2: Compatible TTL driver

ACTUATOR TERMINALS

0: Solder pins**5:** D-Sub connector

DOCUMENTATION _

-: Certificate of conformity C: Calibration certificate R: Calibration certificate + RF curves

Notes

I.C.: Indicator contact - S.C.O.: Self Cut-Off 1. Suppression diodes are already included

GENERAL SPECIFICATIONS

OPERATI	NG MODE	LATC	HING		
Nominal operating voltage (across temperature range)	Vdc	24 (24 to 30)	15 (12 to 20)		
Coil resistance at 23 °C (+/-10%)	Ω	350	120		
Operating current at 23 °C	mA	68	125		
TTL input	High level	3 to 7 Volts: 800 µA max 7 Volts			
TTL input	Low level	0 to 0.8 Volts: 20 µA max 0.8 Volts			
Switching time	ms	15			
Life (Min)	SMA		10 million cycles		
Life (Min)	SMA 2.9	5 million cycles			
Actuator terminals		D-Sub 9 pin female Solder pins			
Weight	g	60			

ENVIRONMENTAL SPECIFICATIONS

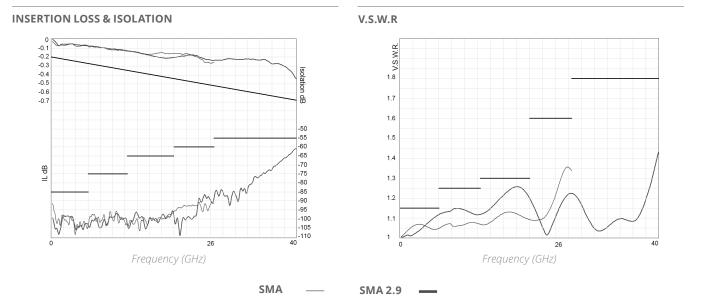
-25 °C to + 75 °C			
-55 °C to +85 °C			
-55 °C to +85 °C (10 cycles)			
10 - 2,000 Hz, 20 g			
16.91 g (rms) 50-2,000 Hz 3 min/axis			
50 g / 11 ms, sawtooth			
15 to 95% relative humidity			
65 °C, 95% RH, 10 days			
15 ft (4.600 meters)			
50 ft (15.240 meters)			



RF PERFORMANCE

PART NUMBER		R59531	R59541		R595F1-		R59581	
Frequency range	GHz	DC to 6	DC to 20 DC to 26.5			DC to 26.5 DC to 40		
Impedance	Ω				50			
Insertion Loss (max)	dB			0.20 + (0	.45 / 26.5) × frequen	cy (GHz)		
Isolation (min)	dB	85	DC to 6 GHz 6 to 12.4 GHz 12.4 to 20 GHz	85 75 65	DC to 6 GHz 6 to 12.4 GHz 12.4 to 20 GHz 20 to 26.5 GHz	85 75 65 60	DC to 6 GHz 6 to 12.4 GHz 12.4 to 20 GHz 20 to 26.5 GHz 26.5 to 40 GHz	85 75 65 60 55
V.S.W.R (max)		1.15	DC to 6 GHz 6 to 12.4 GHz 12.4 to 20 GHz	1.15 1.25 1.30	DC to 6 GHz 6 to 12.4 GHz 12.4 to 20 GHz 20 to 26.5 GHz	1.15 1.25 1.30 1.60	DC to 6 GHz 6 to 12.4 GHz 12.4 to 20 GHz 20 to 26.5 GHz 26.5 to 40 GHz	1.15 1.25 1.30 1.60 1.80
Repeatability (up to 10 million cycles at 25 °C)	dB	0.03 dB maximun 0.05 dB maximun					mun	

TYPICAL RF PERFORMANCE



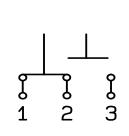


POSITION E1

SWITCH MODEL: NON-TERMINATED SPDT SWITCH

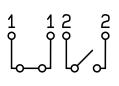
The non-terminated SPDT switch is a single pole double throw switch. This switch is considered "break-before-make."

RF Schematic Diagram



Position Indicator

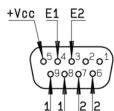
STATE 11



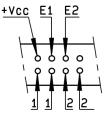
Standard drive option "1"

(Positive common):

- Connect pin +Vcc to supply (+20 Vdc to +32 Vdc)
- Select desired RF path by applying ground to the corresponding "close" pin (Ex: ground pin E1 to switch to position E1. RF path 1-2 closed and RF path 2-3 open)
- To open desired path and close the new RF path, connect ground to the corresponding "close" pin (Ex: ground pin E2 to open RF path 1-2 and close RF path 2-3)

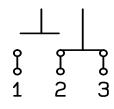


D-Sub connector

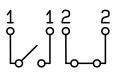


Solder pins



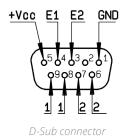


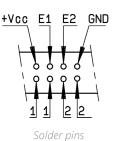
STATE 22



TTL drive option "2"

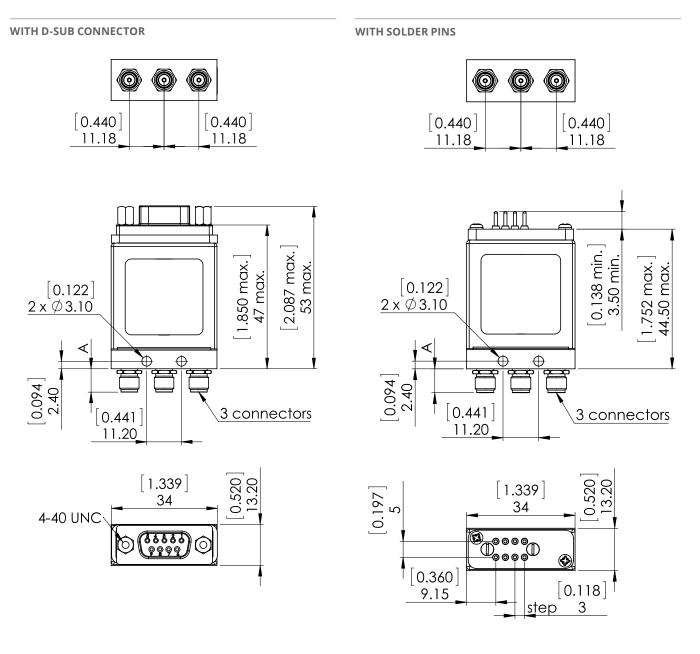
- Connect pin GND to ground
- Connect pin +Vcc to supply (+20 Vdc to +32 Vdc)
- Select (close) desired RF path by applying TTL "High" to the corresponding "drive" pin (Ex: apply TTL "High" to pin E1 to switch to position E1. RF path 1-2 closed and RF path 2-3 open)
- To open desired path and close the new RF path, apply TTL "High" to the "drive" pin which corresponds to the desired RF path (Ex: apply TTL "High" to pin E2)





SMA - SMA 2.9

TYPICAL OUTLINE DRAWING



CONNECTORS	A MAX MM [INCHES]		
SMA	7.7 [0.303]		
SMA 2.9	6.7 [0.264]		

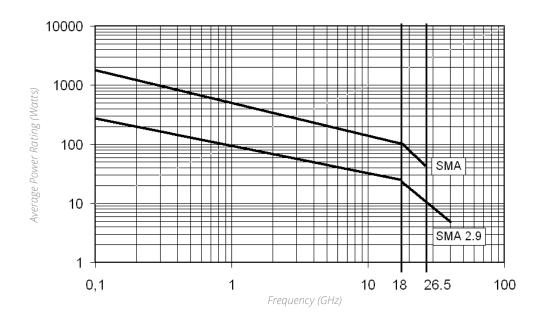
Notes All dimensions are in millimeters [inches].



RF POWER RATING CHART

This graph is based on the following conditions:

- Ambient temperature: + 25 °C
- Sea level
- V.S.W.R.: 1 and cold switching



DERATING FACTOR VERSUS VSWR

The average power input must be reduced for load V.S.W.R. above 1:1

